SIC614A

LF FDX transponder at 125 kHz field frequency with built-in 128 bits encryption (HT AES) REV 1.0

Features Summary

Highlight Features

- Security transponder for the immobilization applications
- Low-frequency FDX technology at 125 kHz field frequency
- Best-in-class of read and write sensitivity
- Authentication based on HT AES crypto algorithm (128 bits secret key)
- Fast mutual authentication
- Qualified AEC-Q100 Grade 3

Interface and Peripheral

- ASK downlink and uplink data transmission
- Manchester and Bi-Phase data coding with RF/32 data rate
- Fully compatible with HT AES command sets and protocols
- ID4A transponder family replacement

Memory

- 32 bits unique device identification
- 128 bits secret key for encrypted authentication
- 32 bits transponder configuration
- 64 bits user memory
- 3,584 bits of extended user memory
- 100,000 erase/write cycles
- 20 years of non-volatile data retention

Operating Conditions

- Carrier frequency f_c is 125 kHz
- Operating temperature: –40°C to 85°C

Package

- Wedge Transponder

Applications

- Immobilizer Key
- Access Control
- Industrial

Revision History

Revision	Date	Description	Change/Update Comment
1.0	27 Jan 2026	Release	1st Initial

Ordering information

Part No.	Description	Package	Marking
PAUDW103EP0SU4AANC3	SIC614A-AN Immobilizer LF FDX with HT AES 128 bits encryption Wedge 125 kHz, Canister, RFID TAG	Wedge	-

Contents

0. Notation 7
0.1 Styles and Fonts for keywords 7
0.2 Abbreviation 8
1. Functional Overview 9
1.1 Details Block Diagram 9
1.2 Block Component Description 10
1.2.1 Analog Front-End (AFE) 10
1.2.2 Digital controller and memory 10
2. Specification 11
2.1 Absolute Maximum Rating 11
2.2 Electrical Characteristic 11
3. Memory organization 12
3.1 EEPROM Organization 12
4. Communication 13
4.1 Initialization Phase (Base station to Transponder) 13
4.2 Downlink Phase (Base station to Transponder) 13
4.3 Uplink Phase (Transponder to Base station) 14
5. Package information 15
5.1 Wedge transponder 15
5.1.1 Wedge dimension 15
6. Packing Specification 16
7. Disclaimer 17

List of Figures

Figure 1-1: SIC614A block diagram 9
Figure 3-1: Memory Structure 12
Figure 4-1: RF protocol of base station to transponder 13
Figure 4-2: RF protocol of transponder to the base station 14
Figure 5-1: Wedge Drawing and dimension 15
Figure 6-1: Product packing 16
Figure 6-2: Inner box dimension 16
Figure 6-3: Outer box dimension 16

List of Tables

Table 0-1: Style and Fonts key word 7
Table 0-2: Abbreviation 8
Table 2-1: Absolute Maximum Rating 11
Table 2-2: AFE Characteristic 11
Table 2-3: EEPROM Characteristic 11
Table 2-4: Environment and Data Reliability 11
Table 4-1: Downlink timing characteristic 13
Table 4-2: Uplink timing characteristic 14
Table 6-1: Canister information 16
Table 6-2: Inner box information 16
Table 6-3: Outer box standard packing information 16

0. Notation

0.1 Styles and Fonts for keywords

This part defines styles and fonts used for the keywords throughout this document. The keywords are the names of signal, register, pin, state of operation, and command. The styles, fonts, and indications are shown in Table 0-1.

Table 0-1: Style and Fonts key word

Symbol	Indication
Signal	Signal name
Register	Register name or Bit name
pin RX	Pin name
"State of Operation"	State of operation
Command	The command name for the RF interface
"Flag"	Flag name in response state

- To refer to a register address and a value in a register, a hexadecimal number proceeding with the letter "0x" is used, for example, 0x0A.
- A symbol "." followed by a number reflecting the bit location starting from 0 to 7 refers to a bit located in a registered address. For example, 0x0A.0 refers to bit 0, the least significant bit, in the register 0x0A.
- A format ".[msb:lsb]" is used after a register value to refer to a set of consecutive bits located in a registered address, such as 0x0A.[3:0] refers to bits 3, 2, 1, and 0 in the register 0x0A.
- To refer to a binary value in some registers, the letter "b" is placed at the end of the binary number, for example, "1010b".
- To refer to the logic level, the number in single quotes '1' and '0' refers to the binary logic level.

0.2 Abbreviation

Table 0-2: Abbreviation

Abbreviation	Term
AFE	Analog Front-end
ASK	Amplitude shift keying
CMD	Command
CRC	Cyclic redundancy check
EEPROM	Electrically Erasable Programmable Read-Only Memory
FDX	Full Duplex
Lock	Permanently disable memory programming
LSB	Least significant bit
MSB	Most significant bit
POR	Power on Reset
RF	Radio Frequency
Rx	Receiver
Tx	Transmitter
TM	Transponder memory
XM	Extended user memory
CM	Configuration memory

1. Functional Overview

The SIC614A is a high-performance Security Transponder for vehicle Immobilization applications, applying mutual authentication between the transponder device and the base station, and it has extended user memory space to support other applications.

The Security Transponder features secure contactless authentication, employing a Secret Key and a random number to cipher any communication between the device and the base station in computed access mode.

1.1 Details Block Diagram

The SIC614A block diagram consists of two parts:

- RF Analog Front-End (RF-AFE)
- Digital Controller and Memory

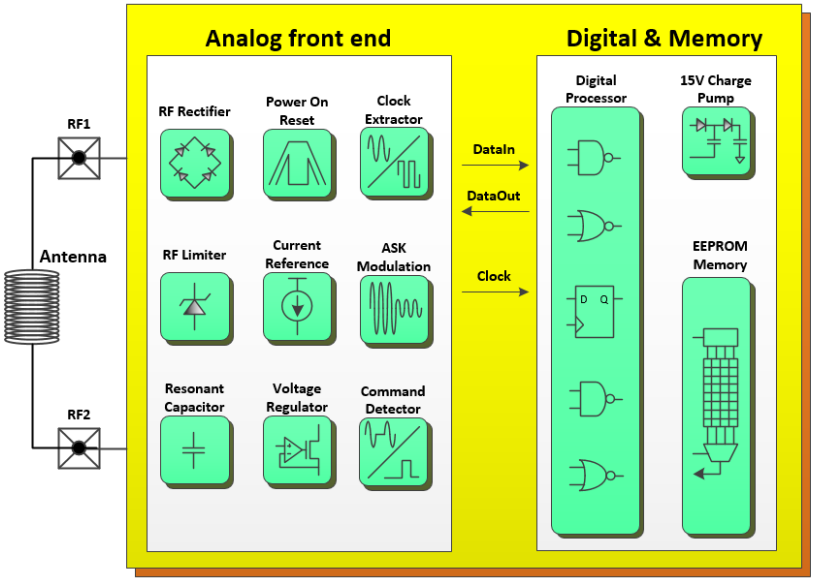

Figure 1-1: SIC614A block diagram

1.2 Block Component Description

1.2.1 Analog Front-End (AFE)

The Analog Front-end (AFE) has RF1 and RF2 terminals to connect to an external antenna. It harvests energy from the induced RF signal in the antenna to supply the internal circuit. The AFE also provides facilities for RF communication, such as a modulator for uplink data communication, a demodulator for downlink data communication, a power-on-reset module, and a clock extractor for data synchronization.

1.2.2 Digital controller and memory

The digital controller controls data transactions between the AFE and the EEPROM. The digital controller handles the following operations:

- Decoding incoming RF downlink commands and encoding RF uplink data/response
- Reading and programming data from/to the EEPROM
- Process authentication using an encryption module

2. Specification

2.1 Absolute Maximum Rating

Conditions above the listed maximum ratings may cause permanent damage to the device. Exposure to the absolute full rating conditions for an extended period may affect the device's reliability. Only one final maximum rating can be applied at a time.

Table 2-1: Absolute Maximum Rating

Parameter	Rating
Operating temperature range	-40 °C to +85 °C
Programming temperature range	-40 °C to +85 °C
Storage temperature range	-40 °C to +125 °C

2.2 Electrical Characteristic

Table 2-2: AFE Characteristic

Parameter	Description	Min	Typ	Max	Unit	Conditions
T_{op}	Operating Temperature	-40	+25	+85	°C	
f_{op}	RF operating frequency		125		kHz	
f_{res}	Resonance frequency	122	125	128	kHz	T_{op} = +25°C
V_H	Clamp RF voltage level		8.3		V	
V_L	Modulating RF voltage level		2.4		V	
$V_{RF,CMD}$	Command reception level	3.0			V	
$V_{RF,PROG}$	Programming RF level	5.0			V	
C_{res}	Resonant capacitor		432		pF	V_H = 3V

Table 2-3: EEPROM Characteristic

Parameter	Description	Min	Typ	Max	Unit	Conditions
T_{ret}	EEPROM Data Retention	20			Years	T_{op} = +50°C
N_{CY}	EEPROM write cycles	100k			Cycles	T_{op} = +25°C

Table 2-4: Environment and Data Reliability

Parameter	Min	Typ	Max	Unit	Conditions
ESD	5			kV	MIL 883 3015.7 (Test 2 times)
Vibration	2.5			Hrs.	IEC 68 part 2-6 (Test 10G,10-2000 kHz, 3-axis)
Drop	100			Times	Test 1.8m free fall
Water Resistant	24			Hrs.	IP68 (Test 1m depth)

3. Memory organization

3.1 EEPROM Organization

The SIC614A memory has 4,096 bits and organizes into 16 blocks, and each block contains 8 pages by 32 bits. The memory sections are split into Transponder Memory (**TM**) – BLOCK 0, Extended User Memory (**XM**) – BLOCK 1 to BLOCK 14, and Configuration Memory (**CM**) – BLOCK 15.

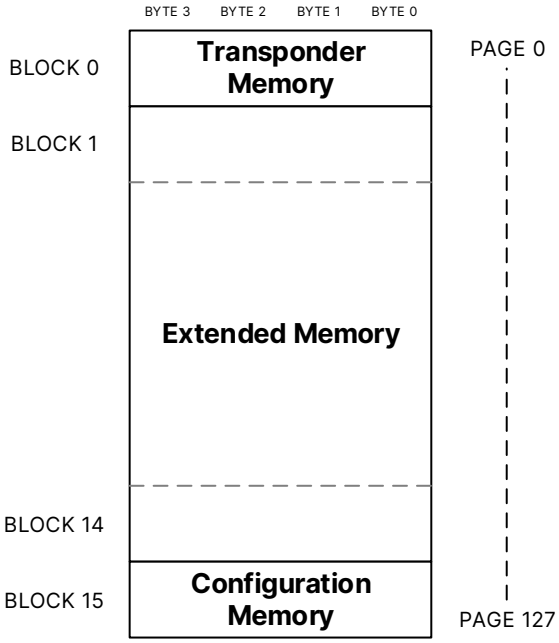

Figure 3-1: Memory Structure

4. Communication

The communication between a base station and transponder consists of three phases:

- Initialization Phase (Base station to Transponder)
- Downlink Mode (Base station to Transponder)
- Uplink Phase (Transponder to Base station)

4.1 Initialization Phase (Base station to Transponder)

This phase starts when a transponder is placed near the base station RF field. The field burst charges up the transponder until there is enough energy level. The Power-On Reset signal is generated and asserted to reset the entire chip. During this phase, chip configuration bits in the memory are read and stored for later use by the digital controller. Then, the transponder stays idle and waits for commands from the reader.

4.2 Downlink Phase (Base station to Transponder)

The reader sends commands to the transponder by turning the RF field OFF and ON with pre-defined intervals. The transponder converts those patterns into the command signal and then sends them to the Digital Controller to translate the operation.

Data information is transmitted to the SIC614A by an amplitude shift keying modulation with a modulation index of 100% (OOK encoding).

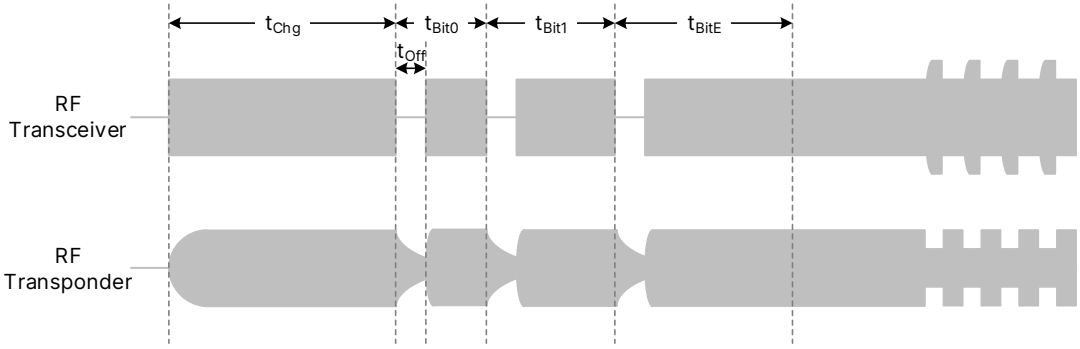

Figure 4-1: RF protocol of base station to transponder

Table 4-1: Downlink timing characteristic

Characteristic at operating frequency (f_{op}) 125 kHz

Parameter	Description	Min	Typ	Max	Unit
t_{Chg}	Charge time (Charge)	500			Cycle
t_{Bit0}	Bit '0' duration (Command)	18	20	22	Cycle
t_{Bit1}	Bit '1' duration (Command)	26	29	32	Cycle
t_{BitE}	End bit duration (Command)	36			Cycle
t_{OffH}	Pulse-off bit	4	6	10	Cycle

4.3 Uplink Phase (Transponder to Base station)

During the uplink phase, the transponder transmits data back to the base station using ASK modulation with the rate of RF/32. The response data bits '0' and '1' are represented by the below data coding types - Manchester or Bi-phase coding, configured by the data coding configuration (**DCS**).

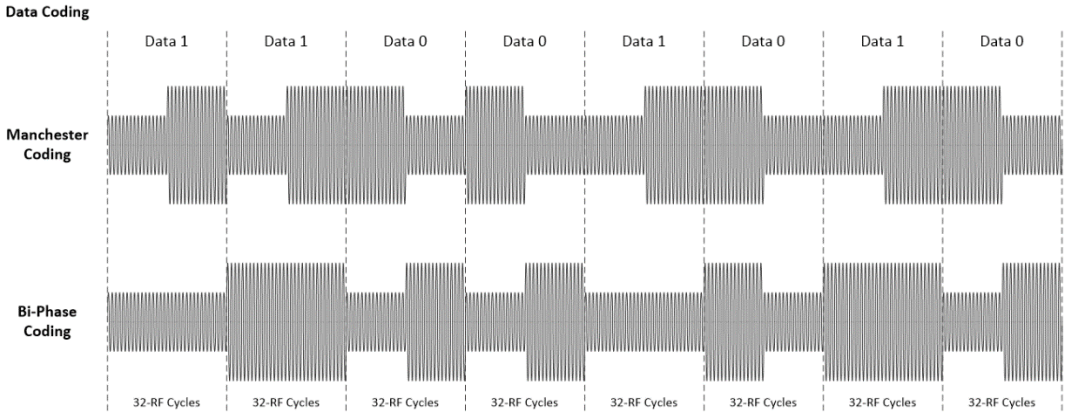

Figure 4-2: RF protocol of transponder to the base station

Table 4-2: Uplink timing characteristic

Parameter	Description	Min	Typ	Max	Unit
Data 0, Data 1	Modulation data duration		32		Cycle

5. Package information

5.1 Wedge transponder

5.1.1 Wedge dimension

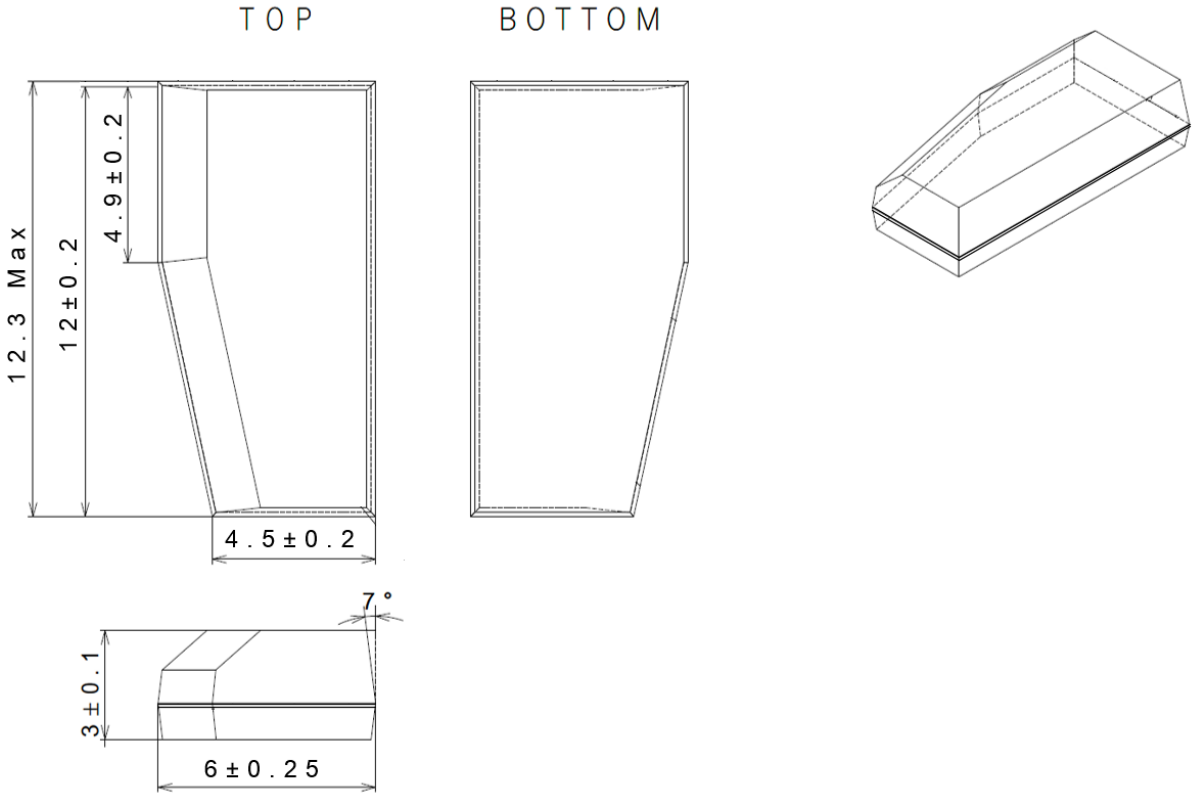

Figure 5-1: Wedge Drawing and dimension

6. Packing Specification

Figure 6-1: Product packing

Table 6-1: Canister information

Packing information	Value	Unit
Canister PVC dimension (OD x H)	ø116 x 128.5	mm
Product quantity per canister	2,000	ea.
Canister weight (Included product)	0.93	kg

Figure 6-2: Inner box dimension

Table 6-2: Inner box information

Packing information	Value	Unit
Inner box dimension (L x W x H)	255 x 255 x 180	mm
Canister quantity per inner box	4	ea.
Inner box weight (Included product)	3.96	kg

Figure 6-3: Outer box dimension

Table 6-3: Outer box standard packing information

Outer box standard	Outer box dimensions L x W x H (mm)	Total maximum weight (kg)	Inner box quantity
1	330 x 240 x 310	4.46	1
2	390 x 380 x 390	8.92	2
3	620 x 390 x 390	17.14	4

The outer box has three standard box sizes depending on the order.

7. Disclaimer

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